

 ELECTRIC CONNECTOR TECHNOLOGY	产品规格书		DOC. No.651-11731-02		Rev: X1	Page: 1/18
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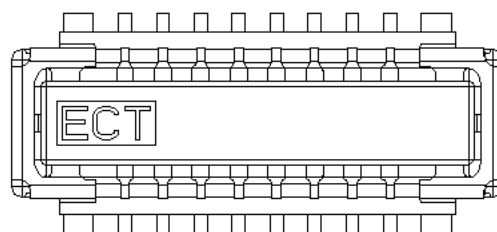
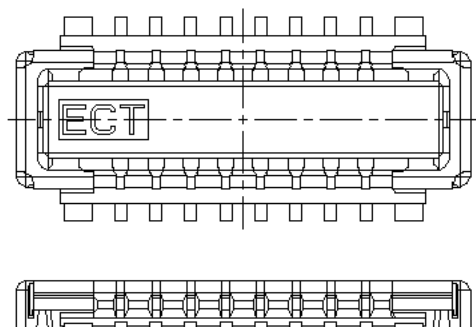
Product Specification				
Rev.	Description	Written/Date	Checked/Date	Approved/Date
X1	BTB RF Plug/Rec Double Row Pitch 0.35mm H0.60mm Series	ZC 09/26/2019	Sean.zhang 09/26/2019	Sean.zhang 09/26/2019

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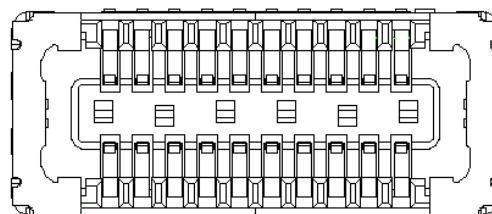
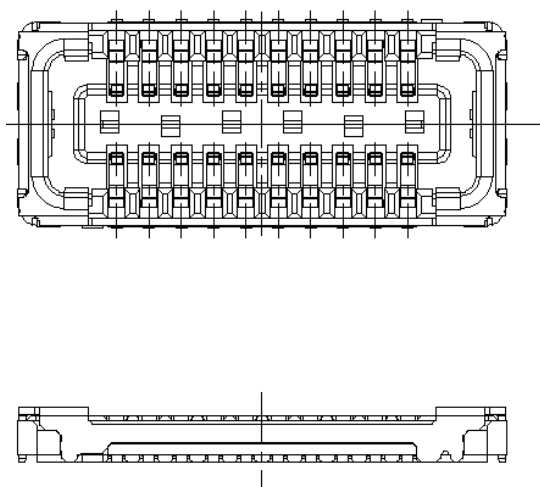
1.0 Scope: This specification covers the requirements for product performance and test methods of ECT's Board To Board RF Double Row Connectors of the part numbers specified as bellow. Product shall be of the design, construction and physical dimensions specified in the applicable product drawing.

本规格书包含了 ECT 板对板 RF 双排连接器（母座&公座)的性能需求
测试方法. 产品的设计，结构，形状和尺寸应该在适当的产品图面中进行描述.

Plug See Appendix.1



Rec See Appendix. 1



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2.0 Rating:

2.1 Voltage Rating: 10V AC/DC

额定电压:10 V AC / DC

2.2 Frequency Range(频率范围) DC 50MHz-12GHz

2.3 Temperature Range: -5℃ to +40℃ storage; -40℃ to +85℃ operating

温度范围: -5℃ to +40℃ storage; -40℃ to +85℃ operating

2.4 Withstand Voltage (耐电压) 100V AC 1 Min.

2.5 Nominal Characteristic Impedance (特征阻抗) 50+/-5 Ohm.

2.6 Power Rating (额定功率) 2W max.(@2GHz).

2.7 V .S .W. R* (电压驻波比) 1.3Max.(DC 0.5~3GHz);1.4Max.(DC 3~6GHz)

1.5Max.(DC 6~12GHz);

2.8 插入损耗/ insertion loss 0.5-3GHz <-0.15dB;3-6GHz < -0.30dB;

6-12GHz <-0.5dB;

2.9 隔离度/isolation >-35dB@3GHz >-30dB@3~6GHz

>-21dB@6-12GHz

3.0 Test Condition:(测试条件)

All tests shall be performed as bellow conditions unless otherwise specified.

所有测试依据以下规格条件执行, 特别说明规格除外。

3.1 Temperature range : +15℃ to +35℃

测试温度范围: +15℃ to +35℃

3.2 Humidity range: 25% to 80%

测试湿度范围: 25% to 80%

3.3 Atmospheric Pressure: 86kPa to 106 kPa (860 to 1060 m bar)

测试大气压力: 86kPa to 106 kPa (860 to 1060 m bar)

4.0 Test Methods and Requirements(测试方法和要求):

4.1 Examination of product(产品外观检验):

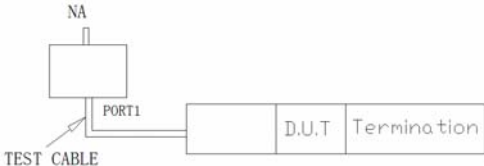
Item 项目	Test Description 测试描述	Test Methods 测试条件	Requirement 要求
4.1.1	Examination of product (Outward Appearance Structure)	EIA 364-18 Shall be confirmed with eyes in accordance with each drawing. Shall be confirmed by using proper	1). Shall meet visual requirement, show no physical damage. 外观没有任何的物理损坏 2). Structure shall be meet the design and

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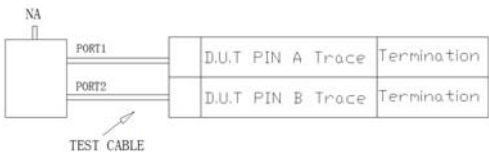
	产品外观结构检验	measuring instruments. 依照图面要求对产品目视检查,再用测量工具按图面要求测量尺寸	dimensional requirements of drawing.外观结构应满足图纸的设计和尺寸要求
4.1.2	Dimension and plating thickness measure 全尺寸, CPK 测量, 镀层厚度.	用测量工具按图面要求测量全尺寸&CPK 用膜厚测试仪, 测试镀层膜厚.	尺寸需满足图纸规格. CPK >1.33. 镀层厚度, 满足图纸规格.
4.1.3	plating thickness 镀层厚度	用膜厚测试仪, 测试镀层膜厚.	1:信号端子 接触区: Ni 2~7.6μm、Au 0.10μm Min 焊接区: Ni 2~7.6μm、0.076~0.20 μm Au 2: 外导体材料 焊接区: Ni 2~7.6μm、0.076~0.20 μm Au

4.2 Electrical Performance(电器性能):

Item 项目	Test Description 测试描述	Test Methods 测试条件	Requirement 要求
4.2.1	Contact Resistance 接触阻抗	JIS C 5402 Make the BTB plugs and receptacles on board be fully mated ,then apply 20mV, 100mA current to the mated specimens , 将焊板的 BTB RF 公母端实配后通电测试, 电流及电压规格: 20mV, 100mA。测试公母端实配后 LLCR	公头和母座组配后测试 , 功能 pin 到功能 pin 接触电阻≤50mΩ , 接地外壳到接地外壳接触电阻≤50mΩ ; 可靠性测试后变化值均≤ 20mΩ
4.2.2	Insulation Resistance 绝缘阻抗	EIA 364-21 (or MIL-STD-202F, Method 302, Test Condition B) Apply a voltage of 200 VDC between adjacent terminals. of the plugs and receptacles. Electrification Time: 2 min 施加 200VDC 到公端&母端相邻两根端子之间, 通电时间: 2 min	1).Initial: 500 MΩ Minimum. 2).After test: 100 MΩ Minimum. 初始值: 500 MΩ Minimum. 测试后: 100 MΩ Minimum.
4.2.3	Dielectric Withstanding Voltage	EIA 364-20 (or MIL-STD-202F, Method 301, Test Condition B) Apply a voltage of 100 VAC between	1). samples no breakdown. 样品无击穿, 烧焦等不良. 2). Cut off current: 2mA Maximum

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	耐电压	adjacent terminals. of the plugs and receptacles. Electrification Time: 1 min. 施加 100VAC 到公端&母端相邻两根端子之间, 通电时间: 1 min			表面漏电: 2 mA Maximum			
4.2.4	V.S.W.R (电压驻波比)	Measure the V.S.W.R as shown in figure 2 by the network analyzer Frequency: DC0.5~12GHz 通过网络分析仪测试 V.S.W.R, 频率范围为 DC0.5~12GHz.如下图所示。 			0~3G 1.3Max 3~6G 1.4Max 6~12G 1.5Max			
4.2.5	insertion loss (插入损耗)	Measure the insertion loss as shown in figure 2 by the network analyzer Frequency: DC0.5~12GHz 通过网络分析仪测试 insertion loss, 频率范围为 DC0.5~12GHz.如下图所示。 			0~3G<-0.15dB; 3~6G< -0.30dB; 6-12GHz <-0.5dB;			

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4.2.6	Isolation (隔离度)	Measure the Isolation as shown in figure 2 by the network analyzer Frequency: DC0.5~12GHz 通过网络分析仪测试 Isolation , 频率范围为 DC0.5~12GHz.如下图所示。 	>-35dB @3GHz >-30dB @3~6G >-21dB@6-12GHz
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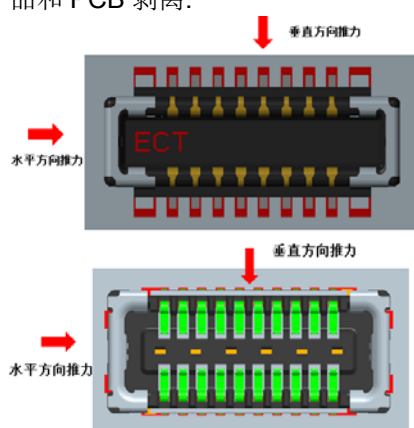
4.3 Mechanical Performance (机械性能):

Item 项目	Test Description 测试描述	Test Methods 测试条件	Requirement 要求
4.3.1	Vibration 震动测试	MIL-STD-202, Method-201 half-sine wave, apply 0.1 A DC current 。 Acceleration:6G(490m/s2) 6g frequency:10-100 Hz; amplitude: 1.50mm sweep time:20 minute the connectors condition is PCB mounting and the plugs mated with receptacles , they must be tested 1hours in each of the 3 axis(X,Y,Z),total 3 hours. 半正弦波, 通以 0.1ADC 电流。 测试频率:10-100 Hz; 振幅: 1.50mm 加速度 6G 波形完成扫描时间:1 minute; 将公母头配合好之后在 X,Y,Z 3 个轴向各测试 1 小时, 共 3 小时。	1).Shall meet visual requirement, show no physical damage. 外观没有任何的物理损坏 2).No discontinuities of 1 μ sec or longer duration. 扣合测试导通瞬断不可超过 1.0 微秒 3)实验后, VSWR 满足规格要求; 插损在按照初始规格增加 0.1dB max 后的规格内
4.3.2	Physical Shock	EIA 364-27 Test Condition A Physical Shock EIA 364-27 Test Condition A (orMIL-STD-202F, Method 213) half-sine wave, apply 0.1ADC current	1).Shall meet visual requirement, show no physical damage.

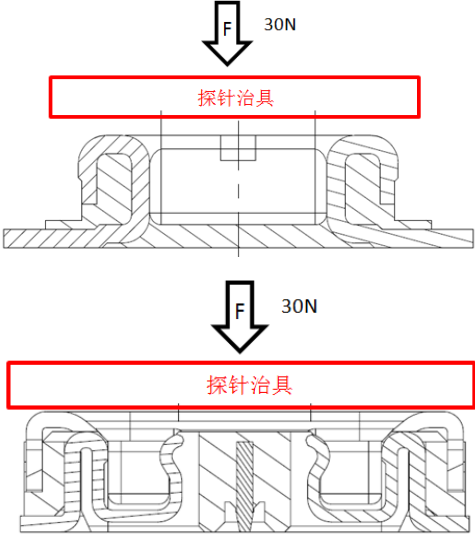
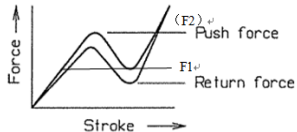
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	机械冲击	Acceleration:75G(490m/s²) duration : 11ms. the connectors condition is PCB mounting and the plugs mated with receptacles , shocking apply to 3 times in each of the 6 direction of 3 axis.18 total shock. 半正弦波, 通以 0.1ADC 电流。 测试的重力加速度:75G (490m/s²) 测试时间: 11ms. 将焊接 PCB 公母头配合, 在 X, Y, Z 三轴 3 个方向各冲击 3 次, 总共 18 次	外观没有任何的物理损坏 2).No discontinuities of 1 μ sec or longer duration. 扣合测试, 导通瞬断不可超过 1.0 微秒 3)实验后, VSWR 满足规格要求; 插损在按照初始规格增加 0.1dB max 后的规格内
4.3.3	Durability 寿命测试	EIA 364-09 Make the specimens that are on board mated, then fix the receptacles to the machine on horizontal or perpendicular direction. Use the machine catch the plugs and separate the specimens, then make the plugs be fully mated with receptacles at a rate of 12.5millimeters/minute on horizontal or perpendicular direction.duration:30 cycles 将焊板的 BTB 公端与母端配合好后将母端水平或垂直固定在测试仪器上, 用仪器夹住公端分离, 然后将公端以 12.5 millimeters/minute 的速度水平或垂直插入焊板母端直到配合到位, 循环 30 次	1).Shall meet visual requirement, show no physical damage. 外观没有任何的物理损坏 2). Contact Resistance value 测试后变化值均≤ 20mΩ
4.3.4	Connector Mating & Unmating Force 插入/拔出力	EIA 364-13 Make the specimens that are on board mated, then fix the receptacles to the machine on horizontal or perpendicular direction. Use the machine catch the plugs and separate the specimens, then make the plugs be fully mated with receptacles at a rate of 12.5millimeters/minute on horizontal or perpendicular direction. 将焊板的 BTB 公端与母端配合好后将母端水平	Mating force(插入力) : 第 1 次 (1ST) Max=35N 第 30 次 (30ST) Max=35N Unmating force : (拔出力) 第 1 次 (1ST) Min= 8N 第 30 次 (30ST) Min= 7N

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		或垂直固定在测试仪器上，用仪器夹住公端分离，然后将公端以 12.5 millimeters/minute 的速度水平或垂直插入焊板母端直到配合到位	
4.3.5	Contact Retention Force 端子保持力	EIA 364-35 The pull speed shall 12.5 mm per minute on the terminal assembled in the housing(Only for female group vertical PIN terminal signal and power PIN) 以 12.5 mm per minute 的速度，将组装在胶芯内的以垂直方向端子拔出（仅针对母座组立式端子信号 PIN 及电源 PIN）	0.2N/Pin Minimum.
4.3.6	SMT 焊接保持力	产品焊接在 PCB 板子上，以 12.5 mm per minute 的速度，从水平方向和垂直方向推产品，使产品和 PCB 剥离。 	水平方向：剥离力 30N Min 垂直方向：剥离力 30N Min
4.3.7	X/Y direction HSG strength X/Y推力测试	BTB on PCB and mating status, make plug and Rec. shear slip by X/Y direction until HSG broken, record curves and get the Max value dates of shear strength. BTB 公母头配合后，沿 X/Y 方向剪切错动，直至破坏，记录 HSG 抗破坏曲线及最大力值；	1)X/Y direction HSG strength need $\geq 35N$ HSG X/Y 方向抗剪切破坏强度不小于 35N

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4.3.8	Guiding test 导向能力测试	Make mating test by BTB Plug&Rec. offset 0.2mm in X/Y direction, set upper limit mating force $\geq 60N$ 公母头 X/Y 方向错位 0.2mm 扣合测试（一端可浮动），扣合力上限设定 $\geq 60N$;	No broken and scrap on Plug&Rec. side 公母无扣合破损及碎屑
4.3.9	resist pressure 抗压力	RF BTB 模拟测试探针的下压情形 	单体在 30N 压力下(模拟测试探针的下压情形)持续 100 秒, 端子不能出现形变
4.3.10	手感指数	设置荷重仪参数, 选择去程-回程, 速度设置在 12.5mm/min; 将测试压头对准 BTB, 用推力机施压, 记录行程-作动力曲线。手感率= $(F2-F1)/F2$ 	手感率 $\geq 60\%$

4.4 Environmental performance (环境性能)			
Item 项目	Test Description 测试描述	Test Methods 测试条件	Requirement 要求
4.4.1	Thermal Shock 热冲击	EIA 364-32, Test Condition I (or MIL-202F, Method 107G Condition A.) specimens shall be separated and exposed 5 cycles as the following conditions.	1). Appearance shall not be distinct damage. 不能出现明显的外观损坏 2). Contact Resistance value: 测试后变化值均 $\leq 20m\Omega$

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		将测试样本公母端分离暴露条件下， -55℃ (30 分钟), +85℃ (30 分钟); 重复 5 次; 零件无损伤			3) 不扣合测试， 试验后各零件外观不能有损伤，试验后样品在空气中放置 2h 后接触电阻与绝缘电阻应符合要求且各零件不能有松动，各镀层表面应无起皮和龟裂等缺陷。 3)实验后， VSWR 满足规格要求；插损在按照初始规格增加 0.1dB max 后的规格内				
4.4.2	Humidity 耐湿性	EIA 364-31, Test Condition A Method III, (or MIL-202F, Method 103B Test Condition B.) The specimens shall be separated and left in the chamber of 25℃ ~65℃ temperature and 90~95% humidity for 96hrs. After test drying in ambient condition for 1 hours 将测试样本公母端分离放在一个恒温恒湿的空间内暴露 96 小时，此空间温度：25℃~65℃，相对湿度：90~95%。测试完成后将样本擦干放置在周围环境中 1 小时			1). Appearance shall not be distinct damage. 不能出现明显的外观损坏 2). Contact Resistance value 测试后变化值均≤20Mω 3)实验后， VSWR 满足规格要求；插损在按照初始规格增加 0.1dB max 后的规格内				
4.4.3	Solder ability 焊接性	EIA 364-52 Make the specimens' tail tested by the last testing step immersion into molten solder at 245+/-5℃ for 3+/-0.5 seconds. 测试样本焊脚浸润在温度为 245+/-5℃的熔融态锡里面 2+/-0.5s。然后将样本拿出。			The surface of the portion to be soldered shall at least 95% covered area must show no voids, pin holes 要求焊脚润锡面积达到浸润面积的 95%以上				
4.4.4	Resistance to soldering heat 耐焊接热	According to the following conditions to test connector. 1. Infrared reflow soldering, the peak temperature of 260 degrees Celsius, reference temperature curve, and the requirements of the SMT2 time; 2. electric soldering iron, requires			Appearance: No abnormality. 外观无明显损伤; Coplanarity of the solder tail should be not beyond 0.10mm				

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		275 degrees 30 seconds, 按下列条件进行测试: 1.红外线回流焊接, 峰值温度260度以下, 可参考温度曲线图(5.0), 且要求SMT2次; 2.电烙铁焊接, 要求 270 度 30 秒,	焊脚平面度不超 0.10mm
4.4.5	Resistance to high storage temperature 高温存储测试	Make the samples be separated and Leave them in the chamber of temperature +85℃ +/-2℃ for 250hr, then it shall be subjected to standard atmospheric condition for 1~2h 将测试样本分离放置在一个+85℃+/-2℃的 空间里暴露 250 小时, 然后在标准环境下放 置 1-2h.	1). Appearance shall not be distinct damage. 不能出现明显的外观损坏 2). Contact Resistance value 测试后变化值均≤20mΩ 3)实验后, VSWR 满足规格要求; 插损在按 照初始规格增加 0.1dB max 后的规格内
4.4.6	resistance to low storage temperature 低温存储测试	Make the samples be separated and Leave them in the chamber of temperature -40℃ +/-2℃ for 96hr, then it shall be subjected to standard atmospheric condition for 1~2h 将测试样本分离放置在一个-40℃+/-3℃的 空间里暴露 96 小时, 然后在标准环境下放 置 1-2h	1). Appearance shall not be distinct damage. 不能出现明显的外观损坏 2). Contact Resistance value 测试后变化值均≤20mΩ
4.4.7	Salt water spray 盐雾测试	EIA 364-16A (MIL-STD-202 METHOD 101) Temperature: 35℃±2℃ 温度: 35℃±2℃ Density of salt water : 5±1% 盐水浓度: 5±1% Duration: 48±2 hours. 持续时间: 48±2 hours.	1). Appearance shall not be distinct damage. 不能出现明显的外观损坏 2). Contact Resistance value 测试后变化 值均≤20mΩ 3)实验后, VSWR 满足规格要求; 插损在按 照初始规格增加 0.1dB max 后的规格内

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4.4.8	Times of Rework Soldering 耐焊接次数	元器件能承受的焊接次数至少为 3 次(常规过炉 top 面和 Bottom 面各一次，加一次位置修复)	1). Appearance shall not be distinct damage. 不能出现明显的外观损坏
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5.0 INFRARED REFLOW CONDITION (回流焊曲线条件)

过炉回流曲线要求	
参数	典型值
均温区要求 (150°C 到 200°C)	100~120 s
峰值温升速率(TL~Tp)	Max: 3°C /s
液态线 (217°C) 以上时间	100~150s
最低回流峰值温度	255°C
250°C 以上时间	Min: 30s
冷却阶段的斜率 (Tp~TL)	Max: -6°C/s
25°C 到 Tp 时间	Max: 8min

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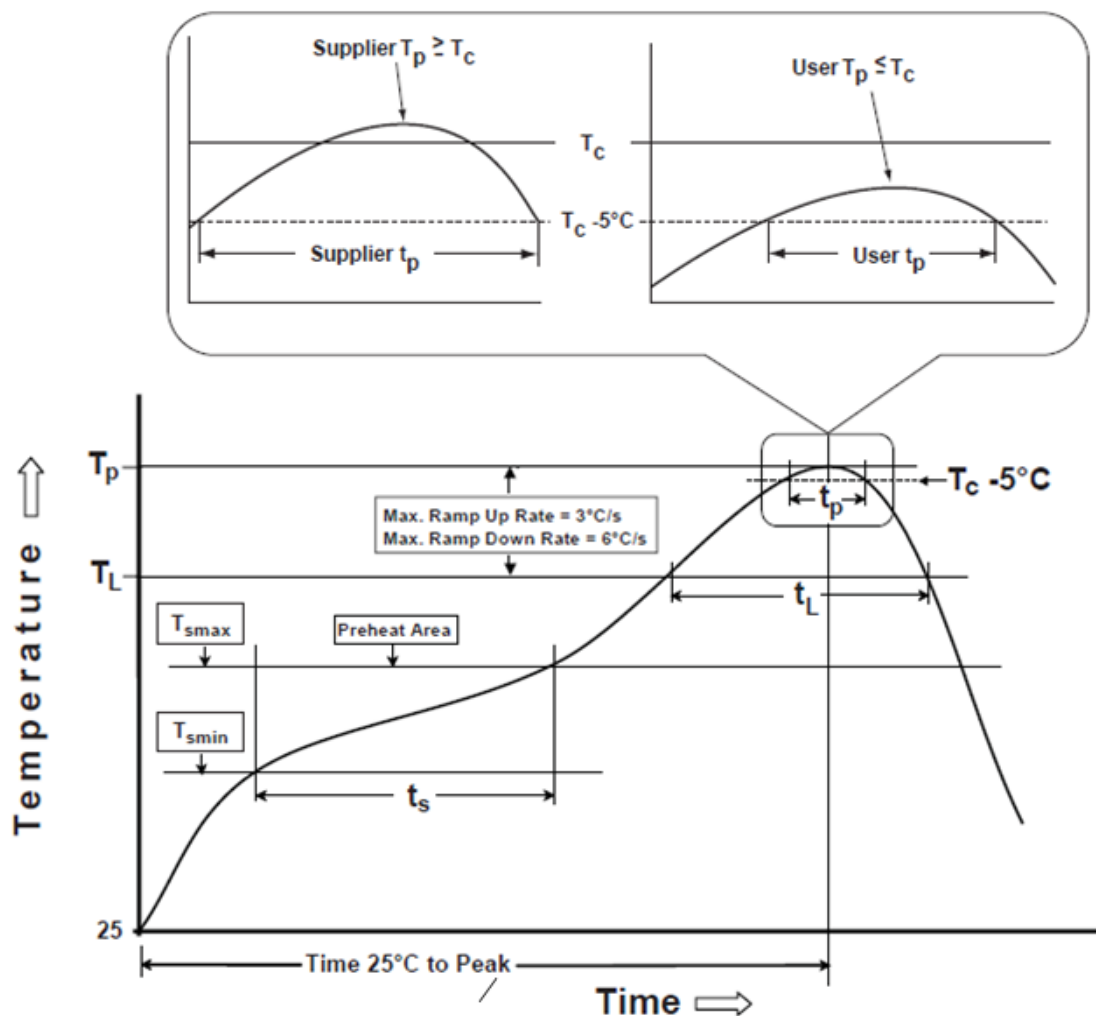


Fig1.Reflow Temperature profile

6.0 INSTRUCTION OF APPLICATION TO USAGE 产品组装的使用说明

This specification is written based on the supposition that the receptacle is mounted on PCB (Hard PCB) and the plug is mounted on FPC. In the case of the receptacle is mounted on FPC and the plug is mounted on PCB (Hard PCB) is also covered. Receptacle contains formable terminal. Please pay attention to un-mating process of connectors if you mount Receptacle on FPC

本说明书根据母座端往PCB基板（硬板）侧实际安装、公座端往FPC（软板）侧，实际安装的设想而作成，同时也适用于公座端往FPC（软板）、公座往PCB基板（硬板）上的实装。母座上的端子容易变形，实装到FPC（软板）上时，特别要注意拔出时的操作。

6.1 MATING (插入操作相关)

6.1.1 HOW TO MATE(INSERTION) 组合方法（插入方法）

After positioning correctly for mating ,then the distance between PCB and FPC is about 1.10mm, insert the

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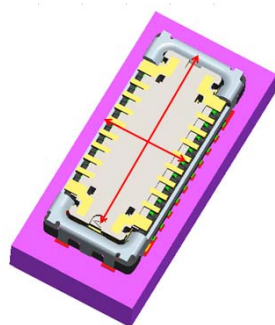
Plug to the receptacle in parallel with each other.

组合时（插入时）请对好位置再进行。位置对好时，PCB基板和FPC软板间的尺寸大概位置在1.10mm之后，请将公座侧与母座侧保持平衡后再插入

Please find correct position at inside wall of receptacle and inside wall of plug

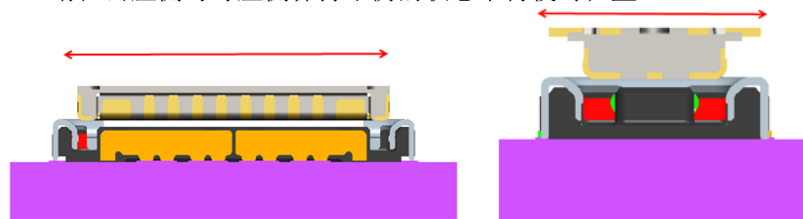
正确的位置调合如右图，请沿母座内壁和公座内壁来进行操作

STEP 1

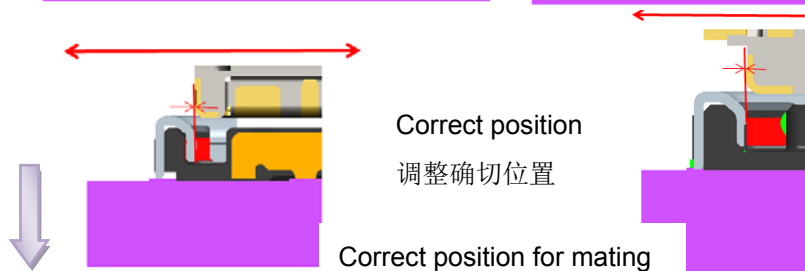
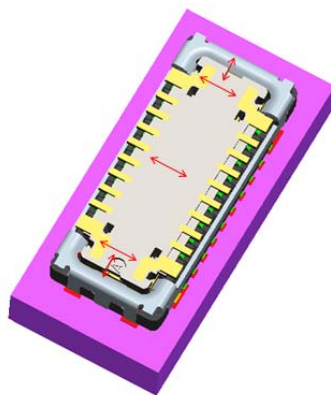


Positioning the plug correctly in parallel with the receptacle

请在公座侧与母座侧保持平衡的状态下再校对位置



STEP 2

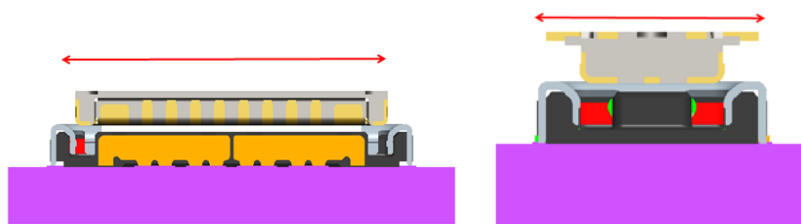


Correct position

调整确切位置

Correct position for mating

正确的嵌合调整位置

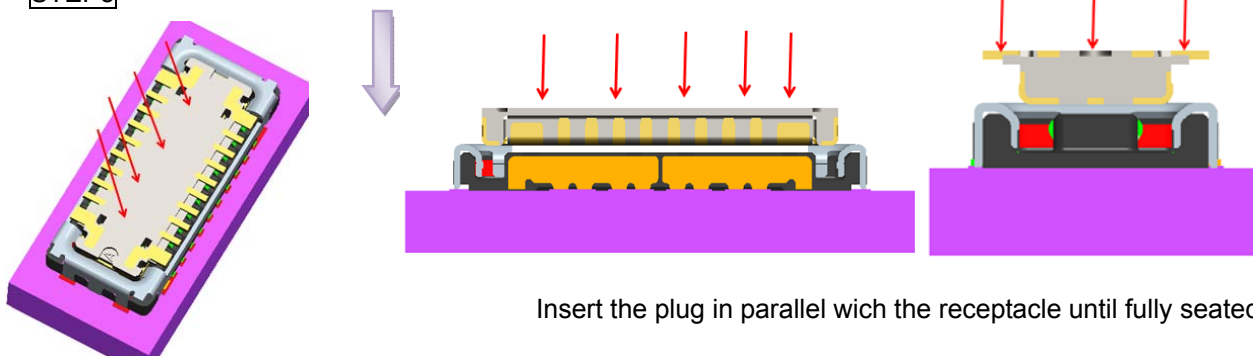


Position the plug correct by adjusting back or forth

轻轻移动公座侧来确认位置调合是否正确

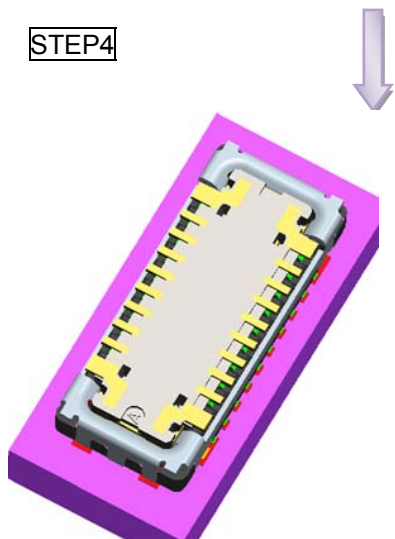
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STEP3



请将公座侧平行压入到母座

STEP4

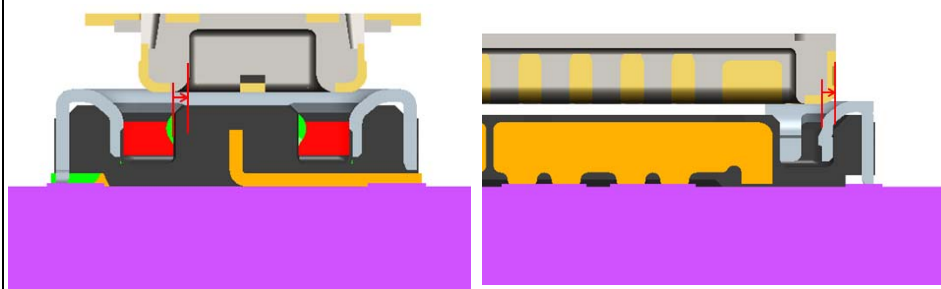


6.2 MATING POSITIONING WITH SLIGHTLY INCLINED 组合时调合位置的方法（位置平行调整困难时）

6.2.1 When operated in "a" Direction(lengthways) 长方向有自由度时

Please keep it within 0.10mm

请保持在 0.10mm 以内



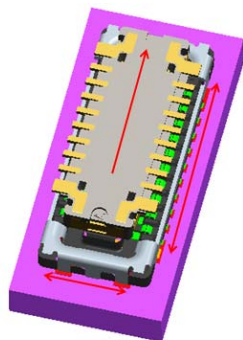
Please find right Position
regarding to procedure
below(请按以下流程来调整位置)

"b" Direction 短方向

"a" Direction (lengthways) 长方向

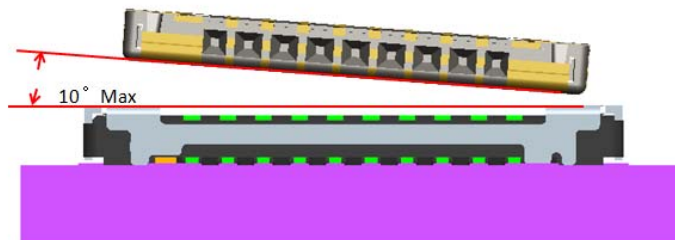
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STEP1



“b” Direction

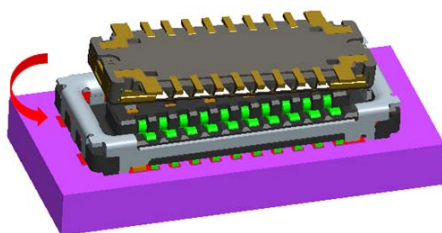
“a” Direction



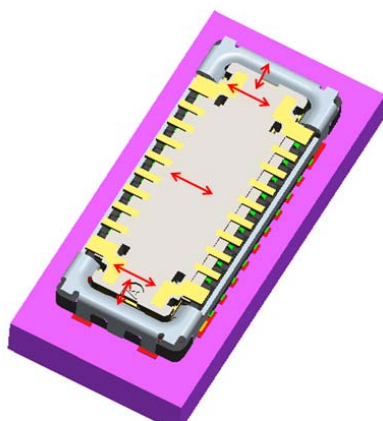
Position for mating by inclining the plug to the receptacle approximately less than 10°

请在公座侧稍微倾斜（10 度以下）的状态下进行组合位置调整操作

STEP2



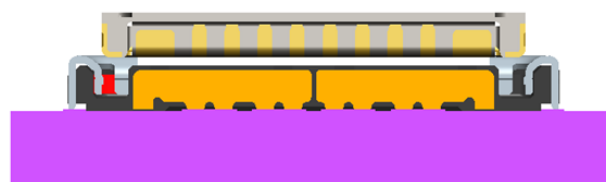
STEP3



Please go to the STEP3 in 6.1.1
请参照 6.1.1 步骤 3 进行下一步操作

Once the plug is positioned over the receptacle
Move it to the parallel position

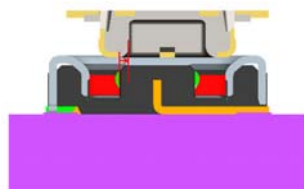
位置调合后，请将公座侧和母座侧保持平行



Position the plug correct by adjusting back or forth
轻轻移动公座侧来确认位置调合是否对位

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6.2.2 When operated in "b" Direction 短方向有自由度时



Please find right Position regarding to procedure below(请按以下流程来调整)



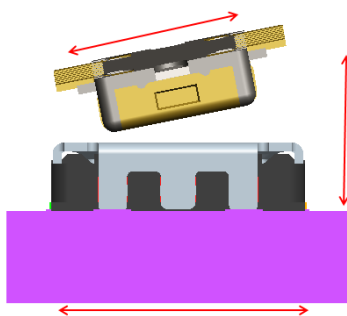
Please keep it within 0.10mm
请保持在 0.10mm 以内

"b" Direction

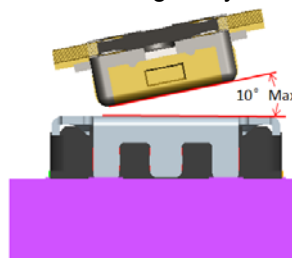
"b" Direction 短方向

"a" Direction (lengthways) 长方向

STEP1



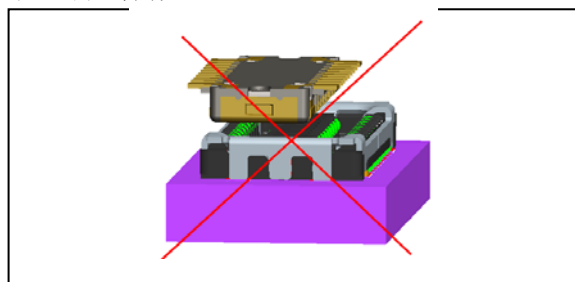
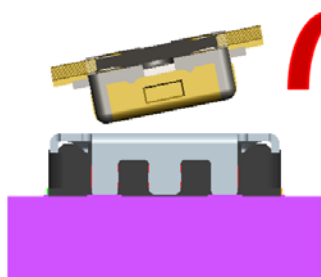
"b" Direction



Position for mating by inclining the plug to the receptacle approximately less than 10°

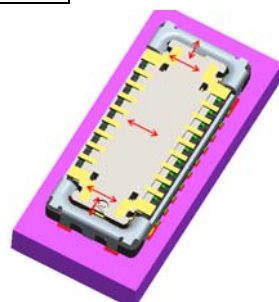
请在公座侧稍微倾斜（10 度以下）的状态下进行组合位置调整操作

STEP2



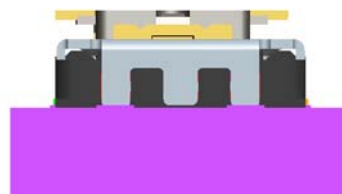
Notes) Pay attention NOT to have the wrong position in "b" Direction 注：请注意位置调合偏差不能太大

STEP3



go to the STEP3 in 6.1.1

请参照 6.1.1 步骤 3 进行下一步操作



Once the plug is positioned over the receptacle Move it to the parallel position

位置调合后，请将公座侧和母座侧保持平行

Position the plug correct by adjusting back or forth
轻轻移动公座侧来确认位置调合是否对位

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6.3 CONNECTOR HANDLING WHEN MATING(组合时操作注意事项)

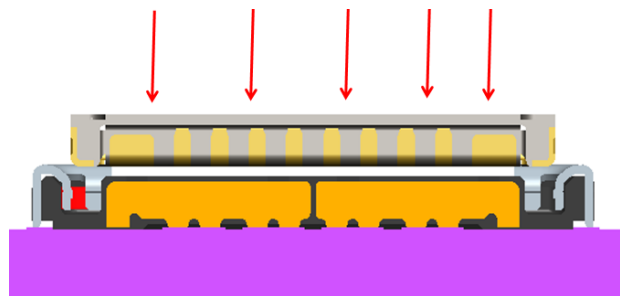
Please DO NOT apply force while mating the receptacle or plug at an angle in the “a” direction(lengthways)
It may cause damage to the connector

请在连接器之间平行的状态下进行组合操作。如果在连接器之间不平行、处在倾斜的状态下组合时，连接器本体之间可能会有干涉，就会有损坏连接器的可能。



Mating with angle(Wrong Handling)

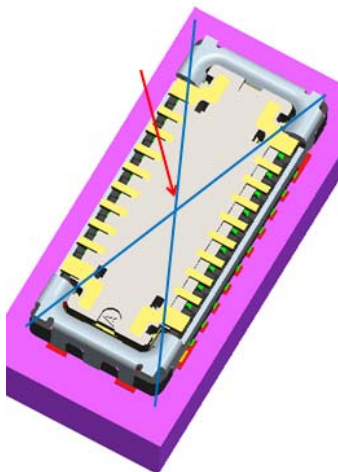
连接器倾斜组合



Mating with Parallel(Correct Handling)

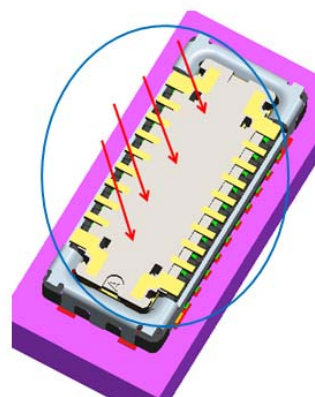
连接器平行组合

This product is downsized comparing with the current products and needs to be handled more carefully.
When mating(inserting), do NOT push the only center of connector but the whole connector in parallel with The receptacle . When pushed only the center of connector , it may cause damage to the connector
本产品比现有产品还要小，连接器的强度较低。组合（插入）时，不能单单只按压连接器中间部，要平行按压整体。FPC 加强板的强度不充足时，如果只按压连接器中间的话，连接器就会有折断的可能。



Pushing only Center(Wrong Handling)

只按压连接器中间部



Pushing Whole Paralleled(Correct Handling)

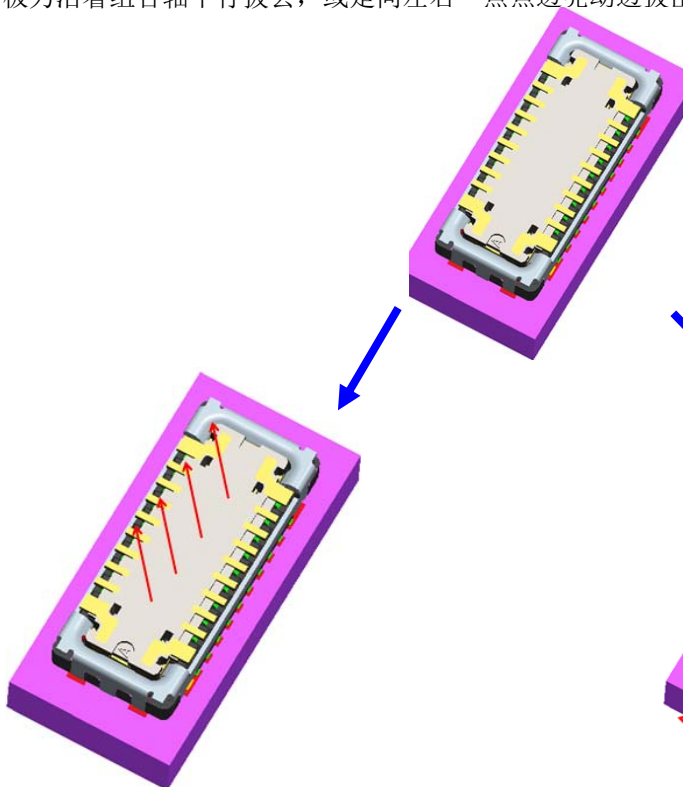
平行按压连接器整体

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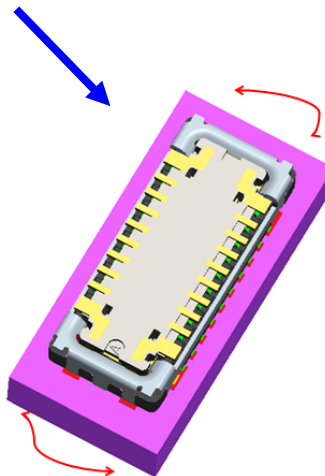
6.4 UN-MATING

6.4.1 HOW TO WITHDRAW 拔出方法

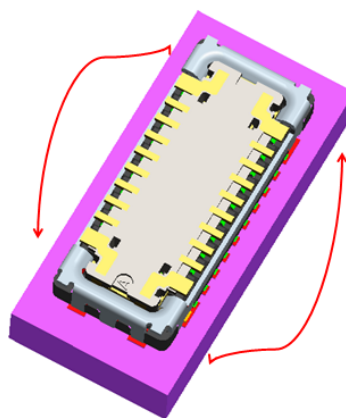
The plug shall be released from the receptacle paralleled to the mated axis or by moving the plug slowly
极力沿着组合轴平行拔去，或是向左右一点点边晃动边拔出。



Releasing the plug paralleled to the mated axis
沿着组合轴向平行拔去



Releasing the plug by moving slowly in "a" direction
(lengthways) 向左右一点点边晃动边拔去（长方向）



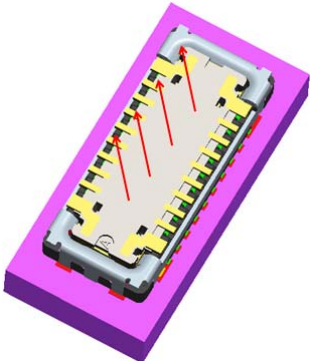
Releasing the plug by moving slowly in "b" direction
向左右一点点边晃动边拔去(短方向)

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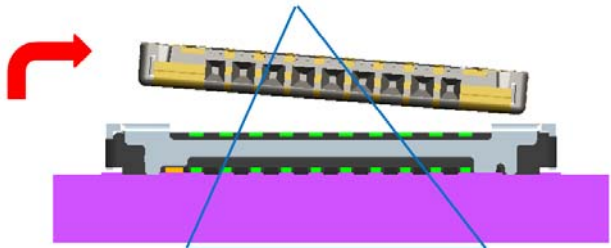
6.4.2 CONNECTOR HANDLING WHEN WITHDRAWING（拔出时操作注意事项）

This product is downsized comparing with the current products and needs to be handled more carefully When un-mating(withdrawing), do NOT twist the plug to release . It may cause damage to connector.

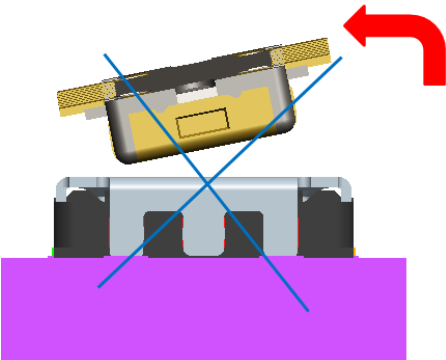
本产品比现有产品还要小，连接器的单体强度较低（单体强度）。如果在过度倾斜状态下拔去的话，连接器就会有破损的可能



Releasing the plug paralleled to the mated axis
沿着组合轴向平行拔去



Slant releasing in “a” Direction (lengthways)
长方向的倾斜拔出



Slant releasing in “b” Direction
短方向的倾斜拔出

Merit and demerit for slant releasing are below

长方向的倾斜拔去方式与短方向的倾斜拔去方式存在以下优点及缺点

	Slant releasing in “a” Direction (lengthways) 长方向的倾斜拔出	Slant releasing in “b” Direction 短方向的倾斜拔出
Merit 优点	1.Not easily cause the damage to the terminals 不容易引起端子变形 2.Hard to be withdrawn 拔出的力度小	None 无特别优点
Demerit 缺点	1. Multiple connector can be damaged plug 多个连接器时拔出时可能会损坏公座	The continuity defect can be caused by damage to the terminals 端子变形风险，同时会存在不导通的可能

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7.0 Test Group		Sample Groups																		
Test Item	Test Description	A	B	C	D	E	F	G	H	I	J	K	L	M	N	O	P	Q	R	S
4.1.1	Examination of product	1	1	1	1,3	1,3	1,3	1,3	1,3	1	1,7	1,6	1,6	1,5	1,6	1,5	1,6	1,5	1,6	1,5
4.1.2	Dimension and plating thickness measure 全尺寸, CPK 测量, 镀层厚度.	2	2	2																
4.1.3	镀层厚度.									2										
4.2.1	Low Level Contact Resistance		3,10								2,8		2,7		2,7		2,7		2,7	
4.2.2	Insulation Resistance		4,11								3,9		3,8		3,8		3,8		3,8	
4.2.3	Dielectric Withstanding Voltage		5,12								4,10		4,9		4,9		4,9		4,9	
4.2.4	V.S.W.R (电压驻波比)			4,7								3,8		3,7		3,7		3,7		3,7
4.2.5	insertion loss (插入损耗)			3,6								2,7		2,6		2,6		2,6		2,6
4.2.6	isolation (隔离度)																			
4.3.1	Vibration										5	4								
4.3.2	Physical shock										6	5								
4.3.3	Durability		7	5																
4.3.4	Mating & Unmating force		6,9																	
4.3.5	Contact Retention Force																			
4.3.6	SMT 焊接保持力				2															
4.3.7	X/Y direction HSGstrength X/Y 推力测试					2														
4.3.8	Guiding test 导向能力测试						2													
4.3.9	resist pressure 抗压力							2												
4.3.10	手感指数		8																	

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4.4.1	Thermal Shock												5	4					
4.4.2	Humidity													5	4				
4.4.3	Solderability																		
4.4.4	Resistance to soldering heat																		
4.4.5	Heat resistance																5	4	
4.4.6	Cold resistance																		
4.4.7	Salt water spray (扣合)															5	4		
4.4.8	Times of Rework Soldering 耐焊接次数							2											
Number of Test Samples (Minimum)		5	5	5	5	5	5	5	5	5	5	5	5	5	5	5	5	5	5

附表 1: 产品料号&品名描述.

The applicable product descriptions and part numbers are as shown in Appendix. 1.

料号 ProductPartNo.	品名 Description
818011731	BTB RF Plug Double Row Pitch 0.35 mm H0.60mm 16pos
818011732	BTB RF Rec Double Row Pitch 0.35 mm H0.60mm 16pos